

Radiation Curing Resins



Product	Solid %	Viscosity	Solvent	OH %	Characteristics
Radiation Curing Resins					
Atrelux UV6154/54 BA	54	25-40 dPas	BA	4,5	Hydroxyl group containing polyacrylic acrylate, curing with isocyanate and radiation (dual cure), non-adhesive and scratch-resistant, for non-yellowing coatings
Atrelux UV100	100	40-60 sec.	no		Radiation curing polyester acrylate, modified with natural fatty acids, for primers, top coats and fillers, good adhesion on wood, very low viscosity, suitable for printing inks
Atrelux UV1500	100	40-60 dPas	no		Polyester acrylic resin for the formulation of UV and electron beam curing varnishes, lacquers, and paints. It is a nearly colourless resin with good reactivity. It forms elastic, scratch and chemical-resistant films with good adhesion properties even on plastic surface;
Atrelux UV1600	100	15-30 dPas	no		Polyester acrylic resin for the formulation of UV and electron beam curing varnishes, lacquers, and paints. It is a nearly colourless resin with good reactivity. It forms elastic, scratch- and chemical-resistant films with good adhesion properties even on plastic surface;
Atrelux UV3000	100	400-600 dPas	no		Epoxy acrylate resin, high reactivity, hard, scratch resistant films, chemical-resistant
Atrelux UV3300	100	120-180 dPas	no		Epoxy acrylate resin, high reactivity, hard, flexible, scratch resistant films, chemical-resistant, corrosion resistant
Atrelux UV3800	100	120-250 dPas	no		Low viscous, low odour epoxy acrylate for the production of UV/Electron beam curing varnishes and lacquers with high hardness, very high reactivity, good pigment wetting, forms hard scratch resistant, durable films, chemical-resistant
Solvent					

WS=White Spirit; AN=Aliphatic Naphtha; IP=Isoparaffin; BA=Butylacetat; X=Xylene; EMP=Ethoxy-, Methoxypropanol; MEK=Methylethylketon; A=Aceton; SN=Solvent Naphta 150; S1= Solvent Naphta 100; BG=Butylglycol;MPA=Methoxypropylacetat; MI=Methyl-Isobutylketon; BGA=Butylglykolacetat; EEP=Ethylethoxypropionat; XBS=conglomeration of Xylol, Butylacetat, Solvent Naphta; EMB: conglomeration of EEP, MPA und BA; TPnB=Dowanol TPnB; Y=further solvent additives; no=solventfree